

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

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(printed on: 2020-07-11 16:54:50)

TOTAL MASS (g) : 0.140508

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.004656 | 1000000 | 33136.8007812 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.047911 | 975000 | 340983.0625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.001179 | 24000 | 8390.95507812 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000015 | 300 | 106.755149841 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000034 | 700 | 241.978347778 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.049139 | 1000000 | 349722.78125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.002585 | 1000000 | 18400.5859375 | | |
| | | External Plating Total: | | | | 0.002585 | 1000000 | 18400.5859375 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000393 | 1000000 | 2796.98486328 | | |
| Internal Plating Total: | | | | 0.000393 | 1000000 | 2796.98486328 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001246 | 750000 | 8867.79492188 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000415 | 250000 | 2953.55908203 | | |
| Die Attach Total: | | | | 0.001661 | 1000000 | 11821.3535156 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.010624 | 130000 | 75611.1171875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.067828 | 830000 | 482732.5625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.002860 | 35000 | 20354.6464844 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000409 | 5000 | 2910.85717773 | | |
| | | Encapsulation Total: | | | | 0.081721 | 1000000 | 581609.1875 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000353 | 1000000 | 2512.3046875 | | |
| | | | | | TOTAL MASS (g) : | 0.140508 | | |